DIE EJECTOR WITH ILLUMINATING UNIT

Abstract

[0041] The invention provides a die ejector (**300**) and a method for die alignment and ejection using said die ejector (**300**) during semiconductor packaging process. The die ejector (**300**) comprises an ejector housing (**320**), a needle holder (**340**), a plurality of ejector needles (**360**), and an illuminating unit (**370**). The illuminating unit (**370**), attached to the ejector housing (**320**), comprises a plurality of light sources (**372**) and a light reflective coating (**374**). The light emitted by the light sources (**372**) is directed by the light reflective coating (**374**) towards the lower side of a wafer (**307**) disposed on an adhesive film (**303**) above a wafer table (**304**). The image of the illuminated wafer (**307**) is captured by a vision inspection unit (**480**) located above the wafer (**307**), and is used for adjusting the position and orientation of the wafer before die ejection.

[0042] FIG. 7A for publication